

**AMENDMENTS TO THE SPECIFICATION**

Please amend the specification to read as follows:

1. On page 5, please replace 2<sup>nd</sup> paragraph with the following paragraph:

In order to achieve the foregoing objects, a method for severing a brittle material substrate according to the present invention is a method for severing a brittle material substrate by scribing, including: a first scribing step of performing scribing in a state in which a protective material is provided on at least one substrate surface of the brittle material substrate, using a cutter wheel with grooves formed in a ridge of the cutter wheel.

inscribing a scribe line on a brittle material substrate, while simultaneously forming a vertical crack extending from the scribe line in a thickness direction of the brittle material substrate,  
wherein the scribe line is formed with a scribe head including a cutter wheel with grooves  
formed in a blade-edge ridge thereof and a tip holder that rotatably supports the cutter wheel,  
and wherein the method includes a first scribing step of pressing and rolling the cutter wheel on  
a protective material by moving the tip holder in a horizontal direction, in a state in which the  
protective material is provided on at least one substrate surface of the brittle material substrate,  
thereby inscribing a scribe line on the brittle material substrate, while simultaneously forming a  
vertical crack extending from the scribe line in a thickness direction of the brittle material  
substrate

2. On page 6, please replace 7<sup>th</sup> paragraph with the following paragraph:

In the case of this brittle material substrate, it is preferable that the above-described severing method includes a second scribing step of performing scribing in a state in which a protective material is provided on a surface of at least one of the first substrate and the second substrate, using a cutter wheel with grooves formed in a ridge of the cutter wheel, after scribing the first substrate in the first scribing step. in the above-described method that the scribe line is  
formed with a scribe head including a cutter wheel with grooves formed in a blade-edge ridge  
thereof and a tip holder that rotatably supports the cutter wheel, and that the method further

includes, before scribing the first substrate in the first scribing step, a second scribing step of pressing and rolling the cutter wheel on a protective material by moving the tip holder in a horizontal direction, in a state in which the protective material is provided on a surface of at least one of the first substrate and the second substrate, thereby inscribing a scribe line on the second substrate, while simultaneously forming a vertical crack extending from the scribe line in a thickness direction of the brittle material substrate.

3. On page 8, please replace 4<sup>th</sup> paragraph with the following paragraph:

Next, a severing apparatus for a brittle material substrate is a severing apparatus for a brittle material substrate that severs a brittle material substrate by scribing, including a first scribing device that performs scribing in a state in which a protective material is applied on at least one substrate surface of the brittle material substrate, using a cutter wheel with grooves formed in a ridge of the cutter wheel.a severing apparatus for a brittle material substrate that inscribes a scribe line on a brittle material substrate, while simultaneously forming a vertical crack extending from the scribe line in a thickness direction of the brittle material substrate, wherein the scribe line is formed with a scribe head including a cutter wheel with grooves formed in a blade-edge ridge thereof and a tip holder that rotatably supports the cutter wheel, and wherein the apparatus includes a first scribing device that presses and rolls the cutter wheel on a protective material by moving the tip holder in a horizontal direction, in a state in which the protective material is provided on at least one substrate surface of the brittle material substrate, thereby inscribing a scribe line on the brittle material substrate, while simultaneously forming a vertical crack extending from the scribe line in a thickness direction of the brittle material substrate.

4. On page 10, please replace 1<sup>st</sup> paragraph with the following paragraph:

In the case of this brittle material substrate, the above-described severing apparatus may include a second scribing device that performs scribing in a state in which a protective material is provided on a surface of at least one of the first substrate and the second substrate, using a cutter wheel with grooves formed in a ridge of the cutter wheel, after scribing the first substrate in the first scribing step. in the above-described severing apparatus, the scribe line may be

formed with a scribe head including a cutter wheel with grooves formed in a blade-edge ridge thereof and a tip holder that rotatably supports the cutter wheel, and the apparatus further may include a second scribing device that presses and rolls the cutter wheel on a protective material by moving the tip holder in a horizontal direction, in a state in which the protective material is provided on a surface of at least one of the first substrate and the second substrate, at the same time of inscribing the scribing line on the first substrate with the first scribing device and before forming the vertical crack extending from the scribe line in a thickness direction of the brittle material substrate, thereby inscribing a scribe line on the second substrate, while simultaneously forming a vertical crack extending from the scribe line in a thickness direction of the brittle material substrate.